



懋昌电源

# MPVX4N65F Series

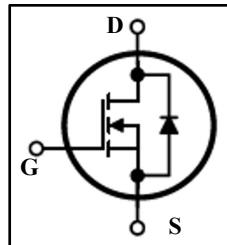
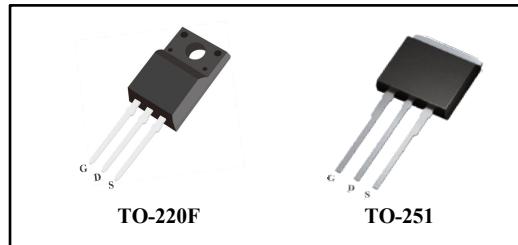
## Power MOSFET

### FEATURES

- $BV_{DSS}$ : 650V,  $I_D=4A$
- $R_{DS(on)}$  : 2.8Ω(Max) @ $V_{GS}=10V$
- Very Low FOM ( $R_{DS(on)} * Q_g$ )
- Excellent stability and uniformity

### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC to DC Converters



### Ordering Information

Type NO.	Marking	Package Code
MPVA4N65F	MPVA4N65F	TO-220F
MPVU4N65F	MPVU4N65F	TO-251

### Absolute Maximum Ratings $T_C = 25^\circ C$ , unless otherwise noted

Parameter	Symbol	Value		Unit
		220F	251	
Drain-Source Voltage ( $V_{GS} = 0V$ )	$V_{DSS}$	650		V
Continuous Drain Current	$I_D$	4		A
Pulsed Drain Current (note1)	$I_{DM}$	16		A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$		V
Single Pulse Avalanche Energy (note2)	$E_{AS}$	224		mJ
Avalanche Current (note1)	$I_{AR}$	4		A
Repetitive Avalanche Energy (note1)	$E_{AR}$	20		mJ
Power Dissipation ( $T_C = 25^\circ C$ )	$P_D$	36	80	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	$-55 \sim +150$		°C

### Thermal Resistance

Parameter	Symbol	Value		Unit
		220F	251	
Thermal Resistance, Junction-to-Case	$R_{thJC}$	3.47	1.66	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	60.0	



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**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

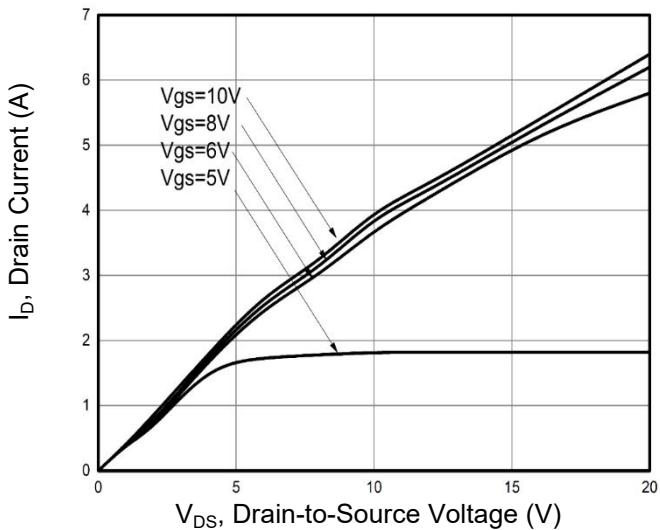
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 30\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	--	4.0	V
Drain-Source On-Resistance (Note4)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 2.0\text{A}$	--	2.3	2.8	$\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	530	--	pF
Output Capacitance	$C_{\text{oss}}$		--	48	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	6	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 400\text{V}, I_D = 4.0\text{A}, V_{\text{GS}} = 10\text{V}$	--	11	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	3	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	4	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 325\text{V}, I_D = 4.0\text{A}, R_G = 25\Omega$	--	20	--	ns
Turn-on Rise Time	$t_r$		--	55	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	70	--	
Turn-off Fall Time	$t_f$		--	50	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	4	A
Pulsed Diode Forward Current	$I_{\text{SM}}$		--	--	16	
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 4.0\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.5	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R = 400\text{V}, I_F = 4.0\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	--	390	--	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		--	2.2	--	$\mu\text{C}$

### Notes

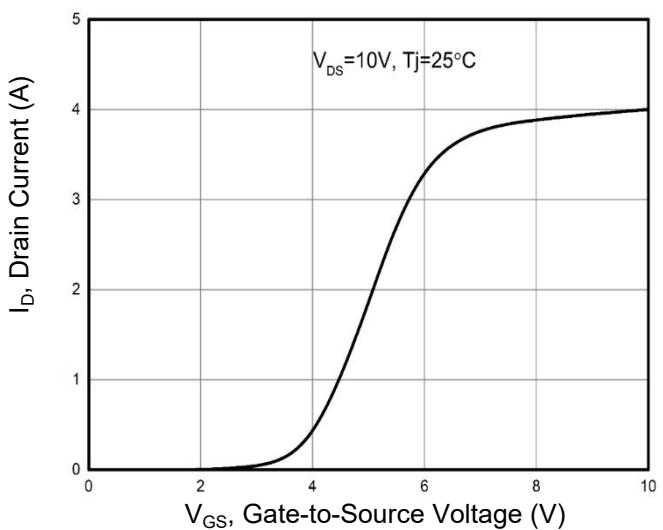
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $L = 10\text{mH}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$
- Essentially independent of operating temperature

**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

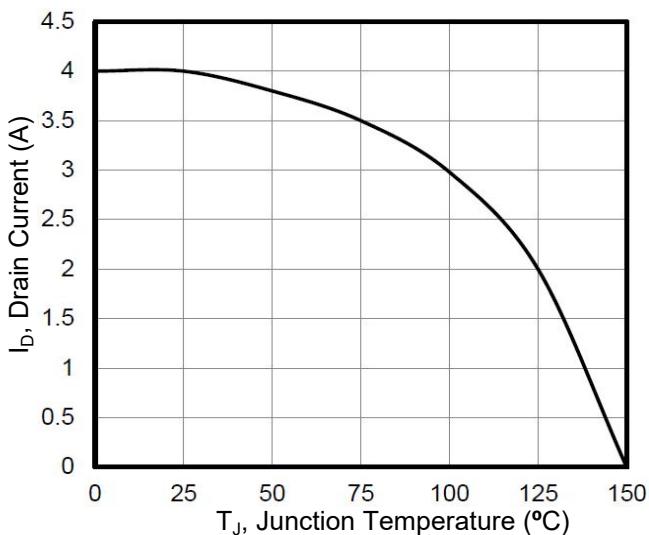
**Figure 1. Output Characteristics**



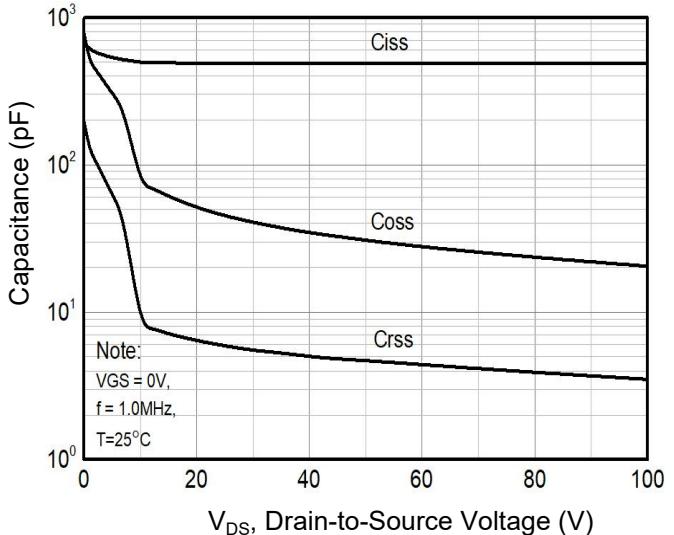
**Figure 2. Transfer Characteristics**



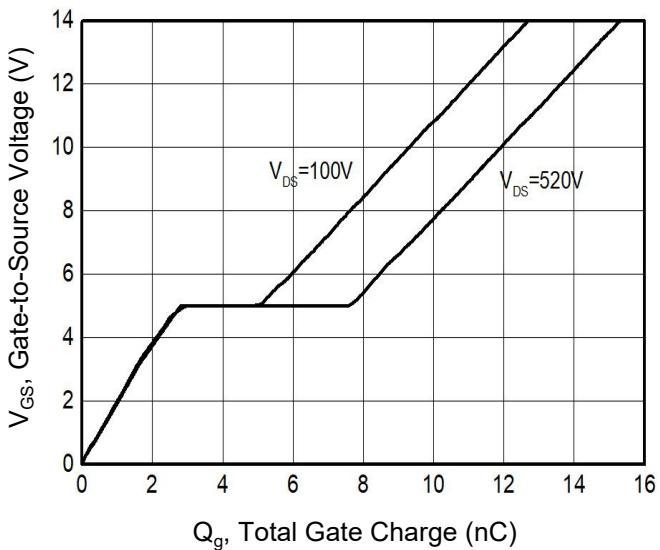
**Figure 3. Drain Current vs. Temperature**



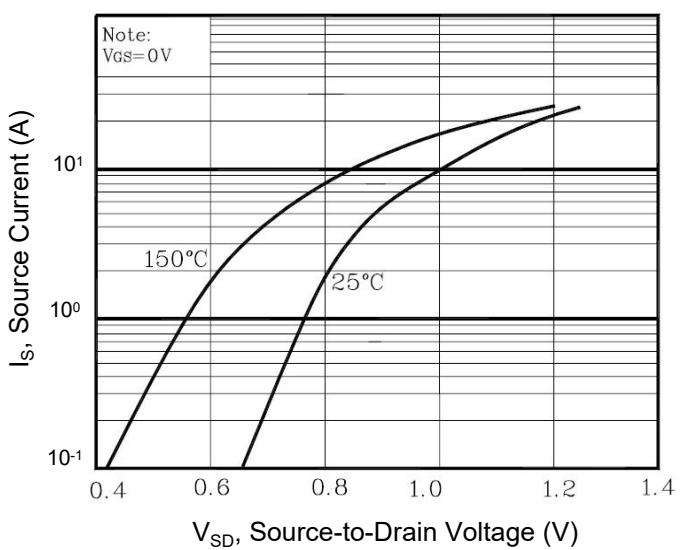
**Figure 4. Capacitance**



**Figure 5. Gate Charge**

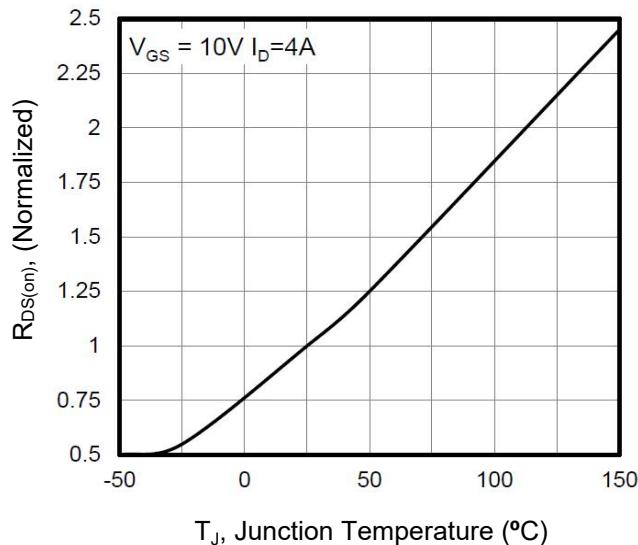


**Figure 6. Body Diode Forward Voltage**

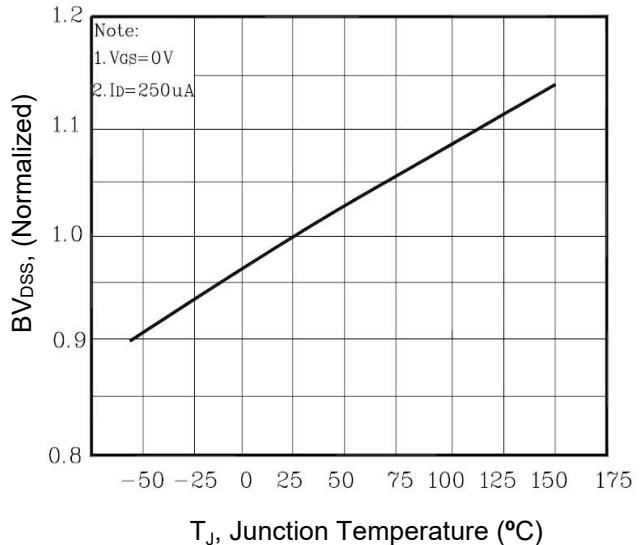


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

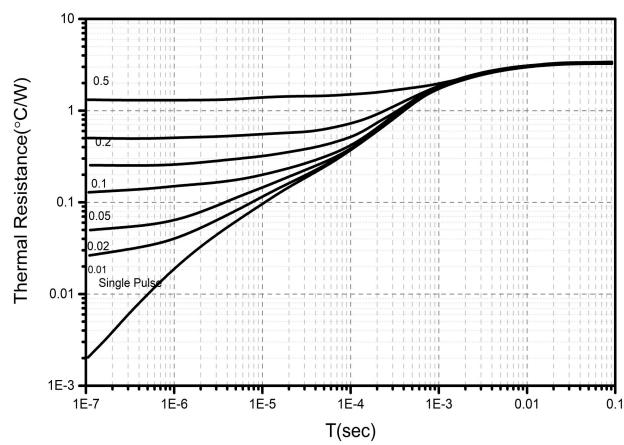
**Figure 7. On-Resistance vs. Temperature**



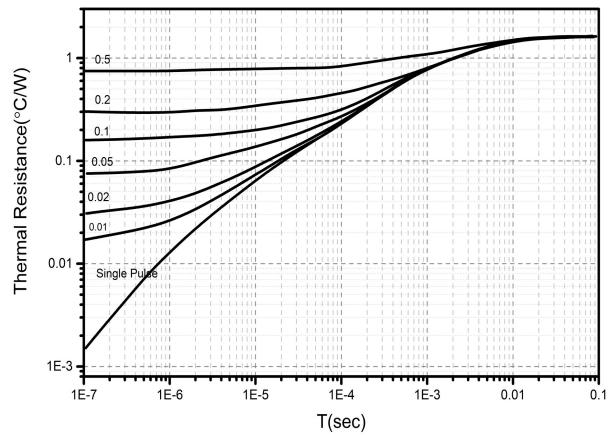
**Figure 8.  $\text{BV}_{DSS}$  vs. Temperature**

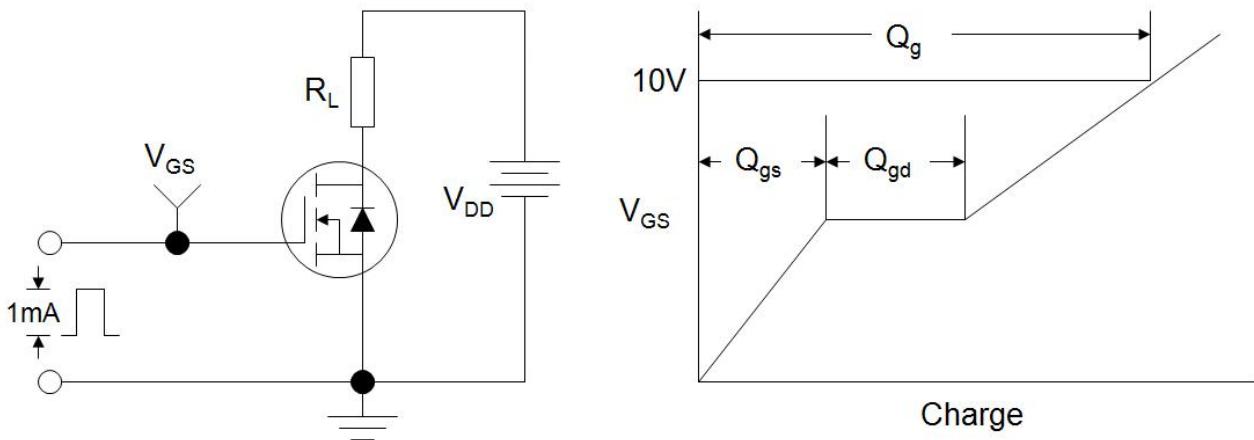
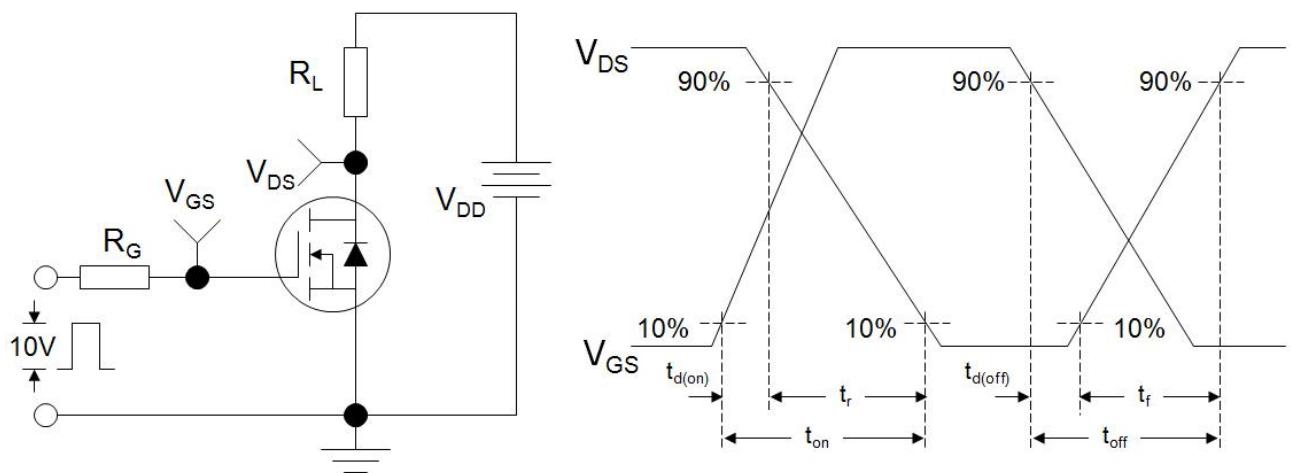
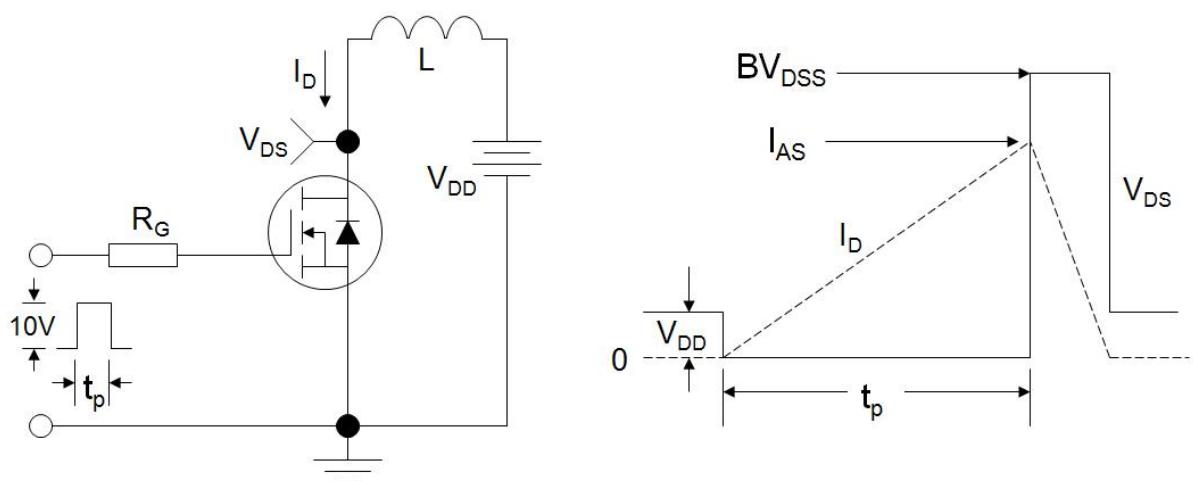


**Figure 9. Transient Thermal Impedance  
(TO-220F)**



**Figure 10. Transient Thermal Impedance  
(TO-251)**

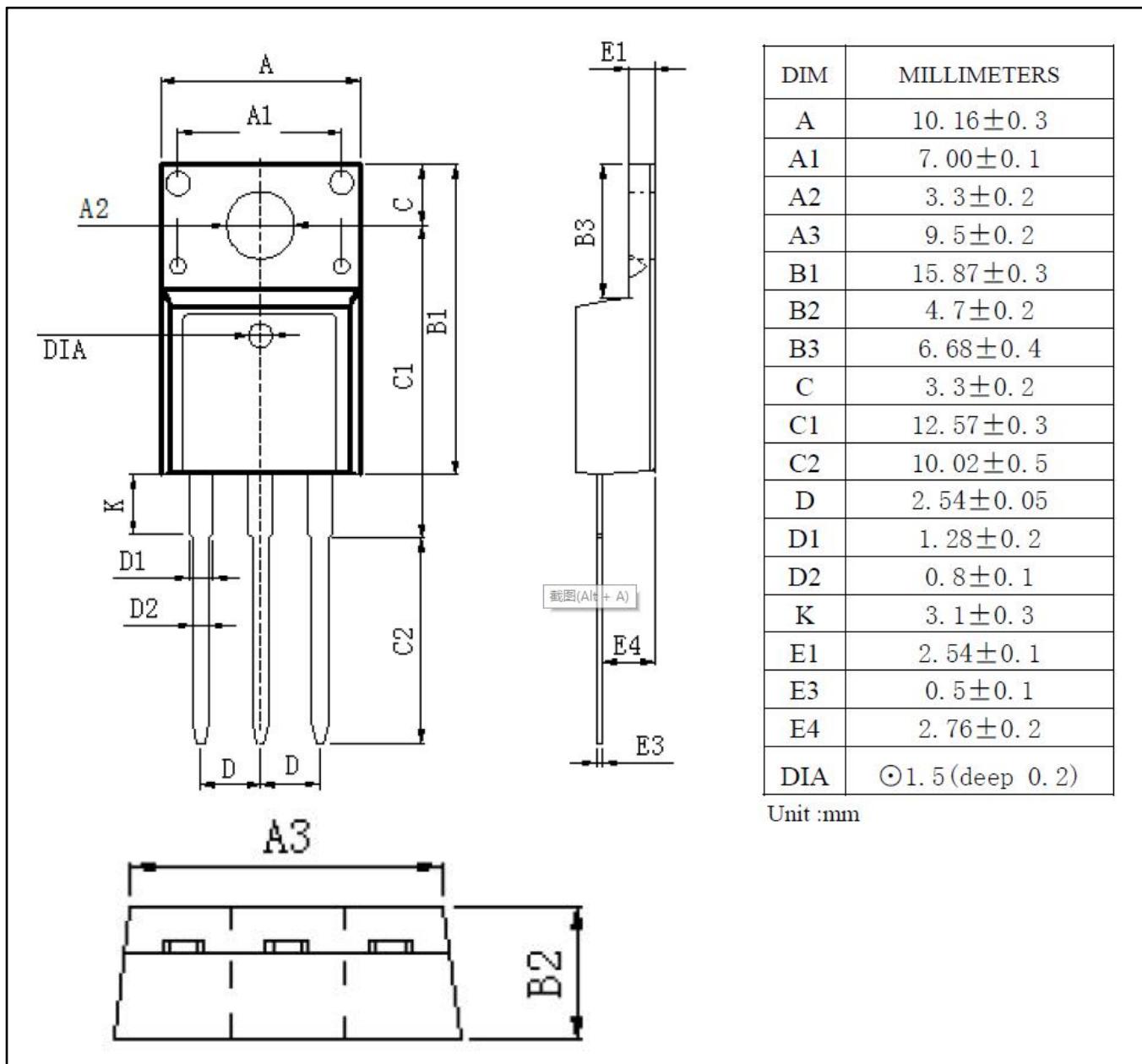


**Figure A: Gate Charge Test Circuit and Waveform**

**Figure B: Resistive Switching Test Circuit and Waveform**

**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**


## Outline Dimension

Unit: mm

### TO-220F



## Outline Dimension

Unit: mm

**TO-251**

The technical drawing illustrates the physical dimensions of the TO-251 power MOSFET package. It includes three views: a top view showing lead heights and overall width; a side view showing height, lead spacing, and lead thickness; and a cross-sectional view showing internal structure and lead placement.

DIM	MILLIMETERS
A	$5.33 \pm 0.2$
A1	$4.33 \pm 0.2$
A2	$5.80 \pm 0.1$
A3	$6.6 \pm 0.2$
B	$14.15 \pm 0.5$
B1	$6.1 \pm 0.3$
B2	$8.0 \pm 0.5$
B3	$4.5 \pm 0.15$
B4	$1.0 \pm 0.1$
B5	$1.05 \pm 0.1$
B6	$0.1 \pm 0.05$
C	$2.3 \pm 0.2$
D	$2.286 \pm 0.05$
D1	$0.60 \pm 0.1$
D2	$0.72 \pm 0.12$
D3	$0.5 \pm 0.08$
D4	$0.5 \pm 0.08$
E	$1.01 \pm 0.2$
DIA	$\odot 1.2$ (deep 0.1)

Unit :mm

单击下面可查看定价，库存，交付和生命周期等信息

[>>芯长征](#)